

OF-SMD5060RGB RED/GREEN/BLUE



ATTENTION

OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES



Description

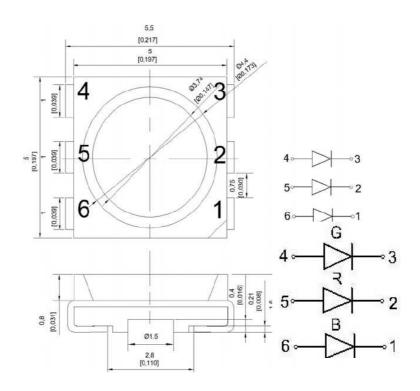
The Green source color devices are made with GaP on SiC Light Emitting Diode. The Red source color devices are made with DH GaAsP/GaP on GaAs substrate Light Emitting Diode.

The Blue source color devices are made with GaN on SiC Light Emitting Diode. Static electricity and surge damage the LEDS. It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs. All devices, equipment and machinery must be electrically grounded.

Features

- CHIPS CAN BE CONTROLLED SEPARATELY.
- SUITABLE FOR ALL SMT ASSEMBLY SOLDER PROCESS.
- AVAILABLE ON TAPE AND REEL.
- PACKAGE: 1000PCS / REEL.

Package Dimensions





- 1. All dimension units are millimeters.
- 2.All dimension tolerance is ±0.2mm unless otherwise noted. 3.An epoxy meniscus may extend about 1.5mm down the leads.

Selection Guide

Part. No	Lens Type		Viewing					
		Green (GaP)		Red (GaAsP/GaP)		Blue (GaN)		Angle
		Min.	Тур.	Min.	Тур.	Min.	Тур.	201/2
OF-SMD5060RGB	Water Clear	600	900	160	250	160	250	100°

Electrical / Optical Characteristics at TA=25℃

Parameter	Symbol	Condition	Red		Green		Blue		Unit
			min.	typ.	min.	typ.	min.	typ.	
Forward Voltage DC	VF	IF=3x20mA	3.0	3.2	1.6	1.9	3.0	3.2	V
Reverse Current	IR	VR=5V			5				uA
Dominant Wavelength	λD	If=20mA	515	520	621	625	470	475	nm
Capacitance	IF(rec)	VF-0V; f=1MHz		45		35		110	pF

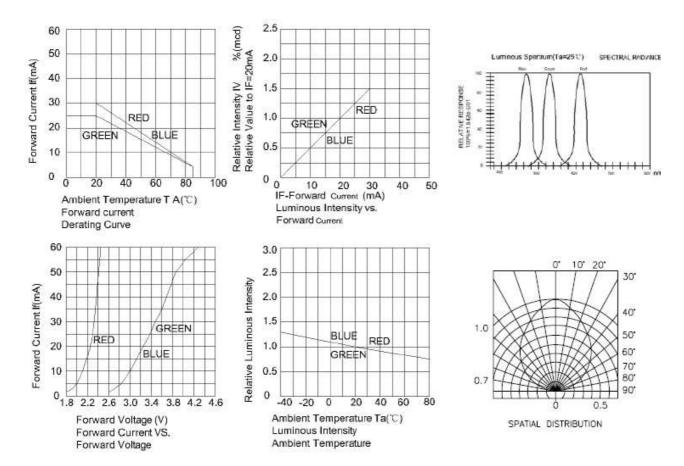
Absolute Maximum Ratings at Ta=25℃

Parameter	Red	Green	Blue	Units	
Power Disspation	90	75	110	mW	
DC Forward Current	25	30	30	mA	
Peak Forward Current	150	185	160	mA	
Reverse Voltage	5	5	5	V	
Operating/Storage Temperature	-40℃ to +85℃				

^{1.} θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

Note:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

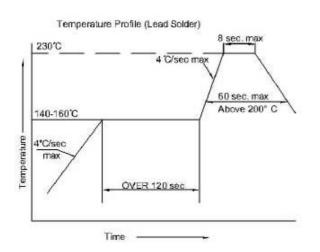


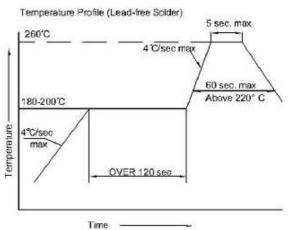


SMT Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first end second soldering process.

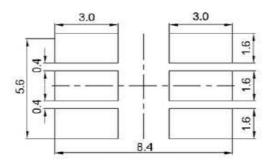






Recommended Soldering Pattern

(Units: mm)



Tape Specifications (Units: mm)

